

WHAT IS CLAIMED IS:

1. A method of probing an electronic device, said electronic device comprising a surface and a plurality of terminals, said method comprising:  
positioning said electronic device and a plurality of probes such that said probes are adjacent ones of said terminals; and  
effecting relative movement of said electronic device and said probes to bring said ones of said terminals into contact with said probes,  
wherein said relative movement comprises a component that is parallel to said surface of said electronic device.
2. The method of claim 1, wherein said ones of said terminals extend from said surface of said electronic device by a distance "d," and said step of positioning said electronic device and a plurality of probes comprises positioning contact portions of said tips less than said distance "d" from said surface of said electronic device.
3. The method of claim 1, wherein said terminals comprise elements raised above the surface of the electronic device.
4. The method of claim 1, wherein said terminals comprise flat pads.
5. The method of claim 1, wherein said terminals comprise partial spheres.
6. The method of claim 1, wherein each said probe comprises a plurality of tips.
7. The method of claim 1, wherein said relative movement further comprises a component that is perpendicular to said surface of said electronic device.
8. The method of claim 1 further comprising testing said electronic device while said probes are in contact with said ones of said terminals.
9. The method of claim 1, wherein said electronic device comprises a semiconductor device.

10. The method of claim 1, wherein said electronic device comprises a semiconductor wafer.
11. The method of claim 1, wherein said electronic device comprises a package for a semiconductor device.
12. The method of claim 1, wherein said electronic device comprises a package for a plurality of semiconductor devices.
13. The method of claim 1, wherein said electronic device comprises a semiconductor die.
14. The method of claim 1, wherein said electronic device comprises a plurality of semiconductor dies.
15. The method of claim 1, wherein said electronic device comprises a printed circuit board.
16. The method of claim 1, wherein said electronic device comprises a ceramic space transformer.
17. The method of claim 1, wherein said electronic device comprises:  
a wiring board; and  
a plurality of semiconductor devices electrically connected to said wiring board.

18. A media containing machine-executable instructions for causing a controller to perform a method of controlling a probing machine, said probing machine comprising a chuck, said method comprising:

generating first signals to position said electronic device and a plurality of probes such that said probes are adjacent terminals of an electronic device disposed on said chuck; and

generating second signals effecting relative movement of said electronic device and said probes to bring said terminals into contact with said probes,

wherein said relative movement comprises a component that is parallel to said surface of said electronic device.

19. The media of claim 18, wherein said terminals extend from a surface of said electronic device by a distance "d," and said step of generating first signals comprises positioning contact portions of said tips less than said distance "d" from said surface of said electronic device.

20. The media of claim 18, wherein each said probe comprises a plurality of tips.